

L Number	Hits	Search Text	DB	Time stamp
1	114566	photolithography or lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
2	1508272	mold\$3 or mould\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
3	9260	(photolithography or lithography) and (mold\$3 or mould\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
4	36986	65/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
5	70	((photolithography or lithography) and (mold\$3 or mould\$3)) and 65/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:59
7	819	fluorine and ((photolithography or lithography) and (mold\$3 or mould\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:59
6	22	fluorine and (((photolithography or lithography) and (mold\$3 or mould\$3)) and 65/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:00
8	1810	fluorine same (sinter\$ or consolidat\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:00
9	20	(fluorine same (sinter\$ or consolidat\$)) and ((photolithography or lithography) and (mold\$3 or mould\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:31
10	8	09/397573	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:30
11	107	(photolithography or lithography) and (fluorine same (sinter\$ or consolidat\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:31
12	20	((fluorine same (sinter\$ or consolidat\$)) and ((photolithography or lithography) and (mold\$3 or mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or abrad\$5 or polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:33

13	20	((fluorine same (sinter\$ or consolidat\$)) and ((photolithography or lithography) and (mold\$3 or mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or abrad\$5 or polish\$3) and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:33
14	20	((fluorine same (sinter\$ or consolidat\$)) and ((photolithography or lithography) and (mold\$3 or mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or abrad\$5 or polish\$3) and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:44
15	8986	(photolithography or lithography) and (fluorine or siF.\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:45
16	238934	surface near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5 or etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:51
17	2378	((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5 or etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:47
18	22	65/.ccIs. and (((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5 or etch\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:47
19	266758	surface near2 (grind\$4 or ground\$3 or abrad\$5 or remov\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:03
20	1656	(surface near2 (grind\$4 or ground\$3 or abrad\$5 or remov\$4)) and ((photolithography or lithography) and (fluorine or siF.\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:52
21	120480	surface near2 (grind\$4 or ground\$3 or abrad\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:52
22	1656	((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or abrad\$5 or remov\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:53
23	197	((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or abrad\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
24	333	(mold\$3 or mould\$3) and (((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5 or etch\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
25	1	(mold\$3 or mould\$3) and II22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02

26	258	(mold\$3 or mould\$3) and (((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or abrad\$5 or remov\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
27	157999	surface near (grind\$4 or ground\$3 or abrad\$5 or remov\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:03
28	11	(surface near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5 or etch\$3)) near4 ingot and (photolithography or lithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:04